



P5MND9P0

Pb RoHS

40V Dual N-Channel MOSFETs

General Description

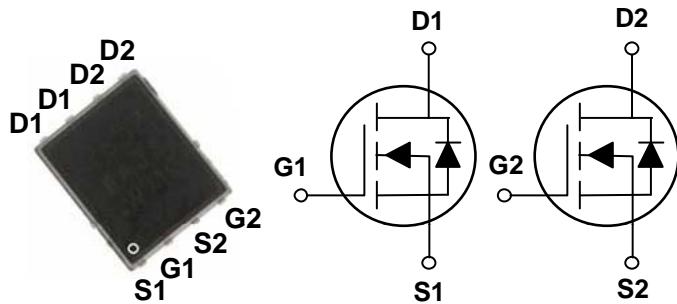
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)}$	I_D
40 V	9 mΩ	30 A

Features

- 40V, 30A, $R_{DS(ON)}=9\text{m}\Omega$ @ $V_{GS}=10\text{V}$
- Fast switching
- Improved dv/dt capability
- Green Device Available

PPAK5X6 Pin Configuration



Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR
- USB Type C

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current - Continuous ($T_C=25^\circ\text{C}$)	30	A
	Drain Current - Continuous ($T_C=100^\circ\text{C}$)	19	A
I_{DM}	Drain Current - Pulsed (NOTE 1)	120	A
EAS	Single Pulse Avalanche Energy (NOTE 2)	64	mJ
IAS	Single Pulse Avalanche Current (NOTE 2)	36	A
P_D	Power Dissipation ($T_C=25^\circ\text{C}$)	46	W
	Power Dissipation - Derate above 25°C	0.37	$\text{W}/^\circ\text{C}$
T_J	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
Marking Code		DC4806T , ND9P0	

Thermal Characteristics

Symbol	Parameter	Typ.	Max	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.7	$^\circ\text{C}/\text{W}$



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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	40	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance (NOTE 3)	$V_{\text{GS}}=10\text{V}$, $I_D=8\text{A}$	---	7.2	9	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=4\text{A}$	---	9.5	12	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1	1.6	2.5	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=10\text{A}$	---	13	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge (NOTE 3、4)	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=8\text{A}$	---	12.2	24	nC
Q_{gs}	Gate-Source Charge (NOTE 3、4)		---	3.3	7	
Q_{gd}	Gate-Drain Charge (NOTE 3、4)		---	6.7	13	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time (NOTE 3、4)	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$, $I_D=1\text{A}$	---	13.2	25	ns
T_r	Rise Time (NOTE 3、4)		---	2.2	5	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time (NOTE 3、4)		---	72	130	
T_f	Fall Time (NOTE 3、4)		---	4.5	10	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	1220	2200	pF
C_{oss}	Output Capacitance		---	130	250	
C_{rss}	Reverse Transfer Capacitance		---	55	110	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	2.2	---	Ω

Guaranteed Avalanche Energy

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{\text{DD}}=25\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=6\text{A}$	1.8	---	---	mJ

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	30	A
I_{SM}	Pulsed Source Current (NOTE 3)		---	---	60	A
V_{SD}	Diode Forward Voltage (NOTE 3)	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=36\text{A}$, $R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.



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Characteristics Curves

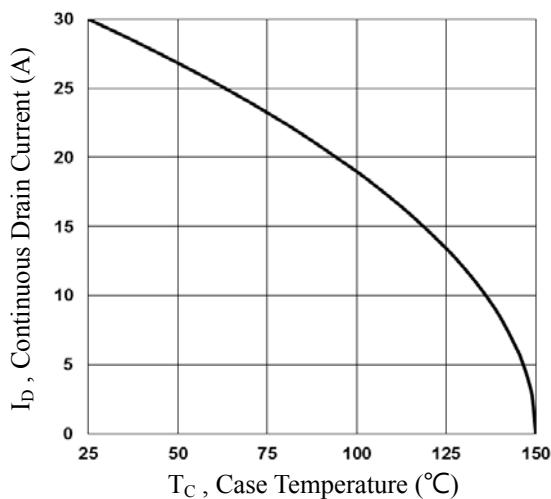


Fig.1 Continuous Drain Current vs. T_c

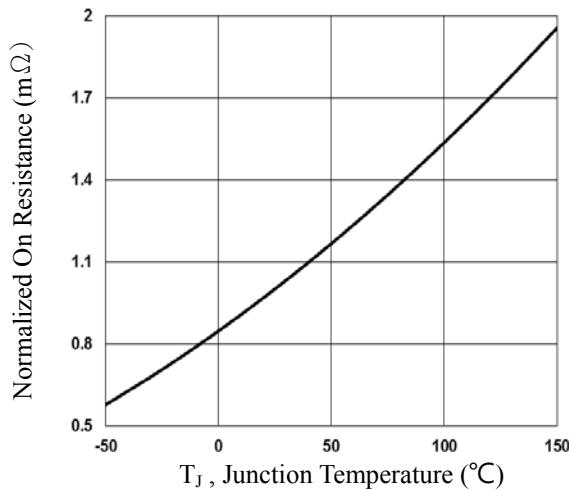


Fig.2 Normalized RDSON vs. T_j

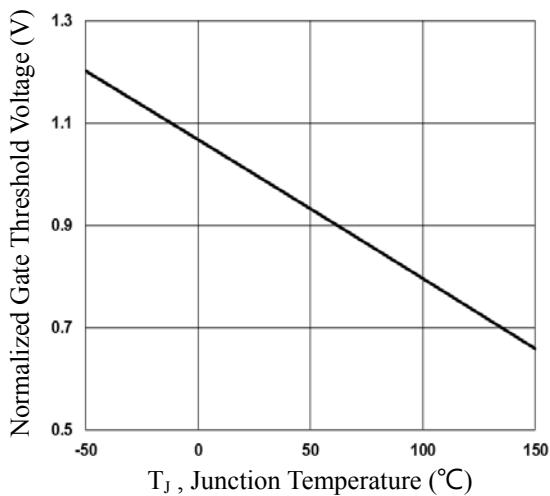


Fig.3 Normalized V_{th} vs. T_j

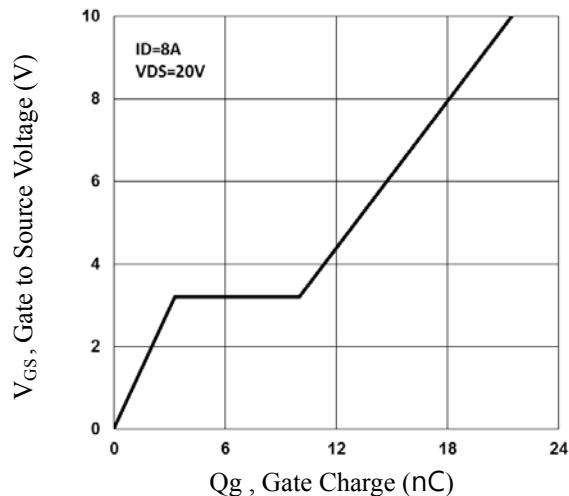


Fig.4 Gate Charge Waveform

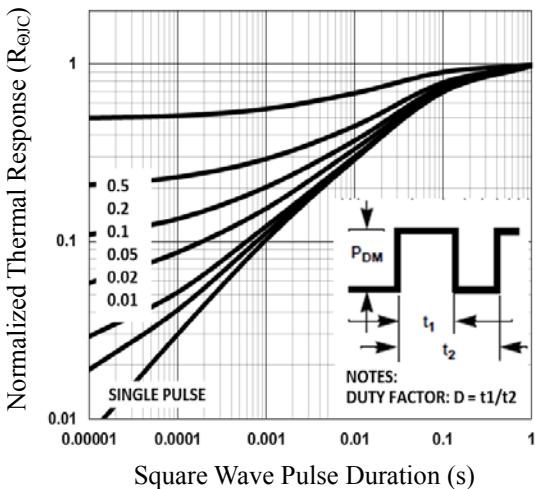


Fig.5 Normalized Transient Impedance

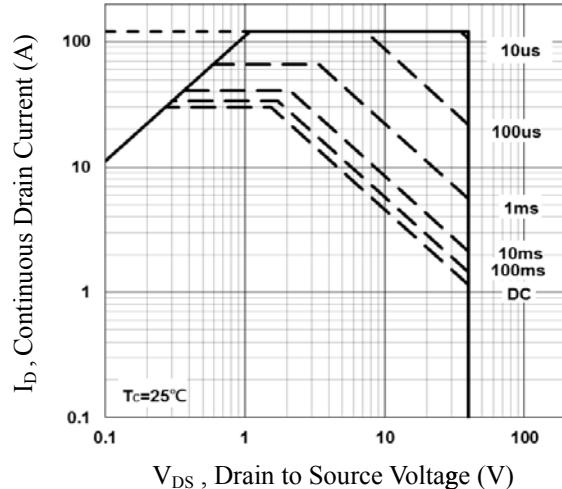


Fig.6 Maximum Safe Operation Area



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Characteristics Curves

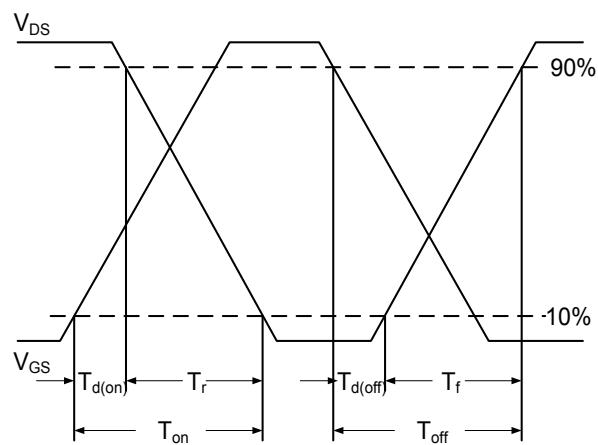


Fig.7 Switching Time Waveform

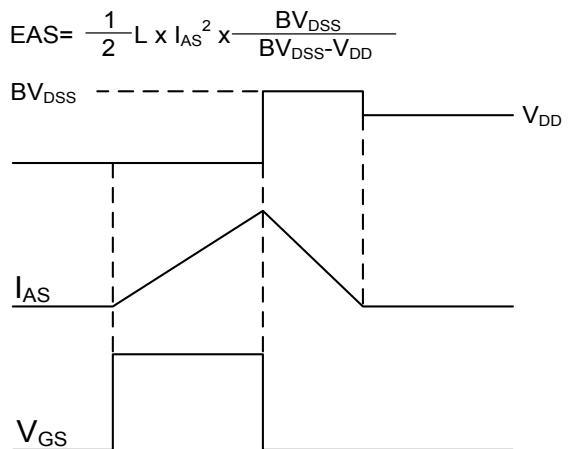


Fig.8 EAS Waveform



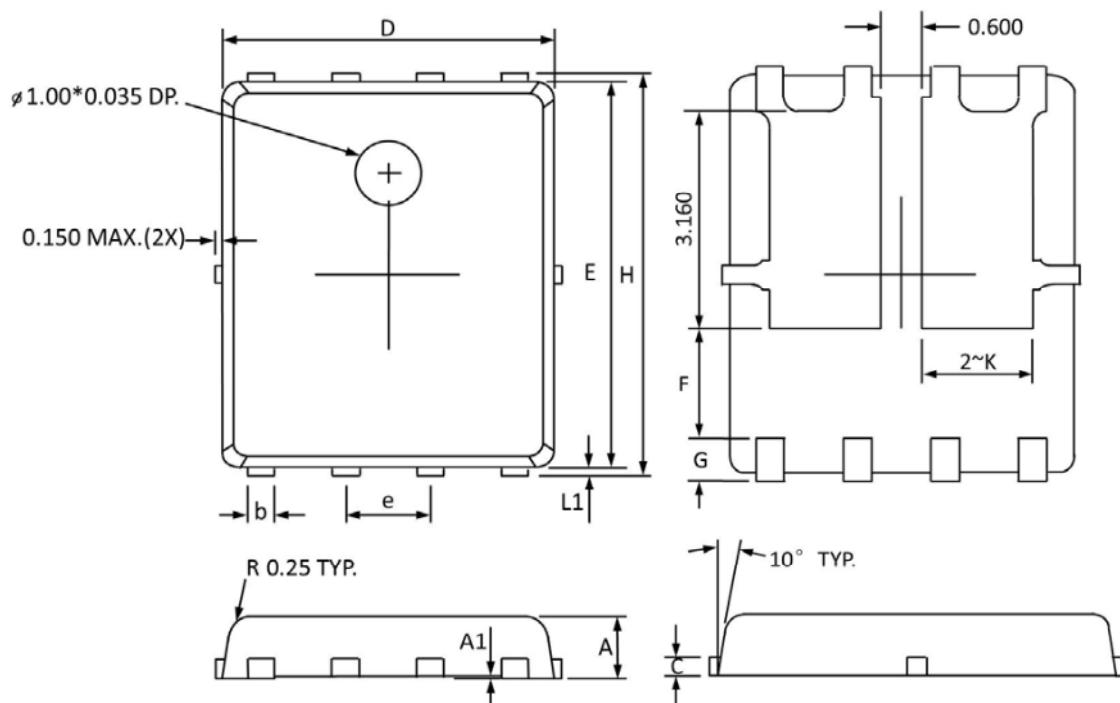
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Package Outline Dimensions

PPAK5X6



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.000	0.032	0.039
A1	0.000	0.005	0.000	0.000
b	0.350	0.490	0.014	0.019
C	0.254 Ref		0.254 Ref	
D	4.900	5.100	0.193	0.200
E	5.700	5.900	0.225	0.232
e	1.27 BSC		1.27 BSC	
F	1.600 Ref		1.600 Ref	
G	0.600 Ref		0.600 Ref	
H	5.950	6.200	0.235	0.244
L1	0.100	0.180	0.004	0.007
K	1.600 Ref		1.600 Ref	



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